SN54LV161A, SN74LV161A
4-BIT SYNCHRONOUS BINARY COUNTERS
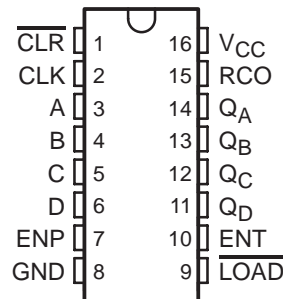
- **2-V to 5.5-V V_{CC} Operation**
- **Max t_{pd} of 9.5 ns at 5 V**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Typical V_{OHV} (Output V_{OH} Undershoot) >2.3 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Support Mixed-Mode Voltage Operation on All Ports**
- **Internal Look-Ahead for Fast Counting**
- **Carry Output for n-Bit Cascading**
- **Synchronous Counting**
- **Synchronously Programmable**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
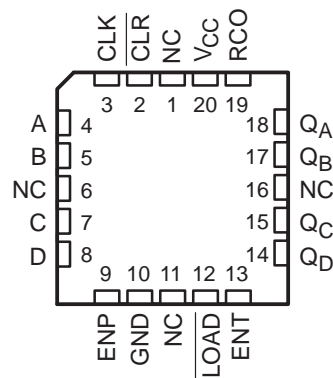 - **1000-V Charged-Device Model (C101)**

description/ordering information

The 'LV161A devices are 4-bit synchronous binary counters designed for 2-V to 5.5-V V_{CC} operation.

SN54LV161A . . . J OR W PACKAGE
SN74LV161A . . . D, DB, DGV, NS, OR PW PACKAGE
(TOP VIEW)

$\overline{CLR}$	1	16	V_{CC}
CLK	2	15	RCO
A	3	14	Q_A
B	4	13	Q_B
C	5	12	Q_C
D	6	11	Q_D
ENP	7	10	ENT
GND	8	9	$\overline{LOAD}$

SN54LV161A . . . FK PACKAGE
(TOP VIEW)

Top pins: CLK, $\overline{CLR}$, NC, V_{CC}, RCO (3, 2, 1, 20, 19)

A	4	18	Q_A
B	5	17	Q_B
NC	6	16	NC
C	7	15	Q_C
D	8	14	Q_D

Bottom pins: ENP, GND, NC, $\overline{LOAD}$, ENT (9, 10, 11, 12, 13)

NC – No internal connection

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	SOIC – D	Tube of 40	SN74LV161AD	LV161A
		Reel of 2500	SN74LV161ADR	
	SOP – NS	Reel of 2000	SN74LV161ANSR	74LV161A
	SSOP – DB	Reel of 2000	SN74LV161ADBR	LV161A
	TSSOP – PW	Tube of 90	SN74LV161APW	LV161A
		Reel of 2000	SN74LV161APWR	
		Reel of 250	SN74LV161APWT	
	TVSOP – DGV	Reel of 2000	SN74LV161ADGVR	LV161A
−55°C to 125°C	CDIP – J	Tube of 25	SNJ54LV161AJ	SNJ54LV161AJ
	CFP – W	Tube of 150	SNJ54LV161AW	SNJ54LV161AW
	LCCC – FK	Tube of 55	SNJ54LV161AFK	SNJ54LV161AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TEXAS INSTRUMENTS

description/ordering information (continued)

These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting designs. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when so instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes that normally are associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

These counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. As presetting is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

The clear function for the 'LV161A devices is asynchronous. A low level at the clear ($\overline{CLR}$) input sets all four of the flip-flop outputs low, regardless of the levels of the CLK, load ($\overline{LOAD}$), or enable inputs.

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. Instrumental in accomplishing this function are ENP, ENT, and a ripple-carry output (RCO). Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with Q_A high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or $\overline{LOAD}$) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

FUNCTION TABLE

INPUTS					OUTPUTS				FUNCTION
$\overline{CLR}$	$\overline{LOAD}$	ENP	ENT	CLK	QA	QB	QC	QD	
L	X	X	X	X	L	L	L	L	Reset to "0"
H	L	X	X	↑	A	B	C	D	Preset Data
H	H	X	L	↑	No Change				No Count
H	H	L	X	↑	No Change				No Count
H	H	H	H	↑	Count up				Count
H	X	X	X	↑	No Change				No Count

logic diagram (positive logic)
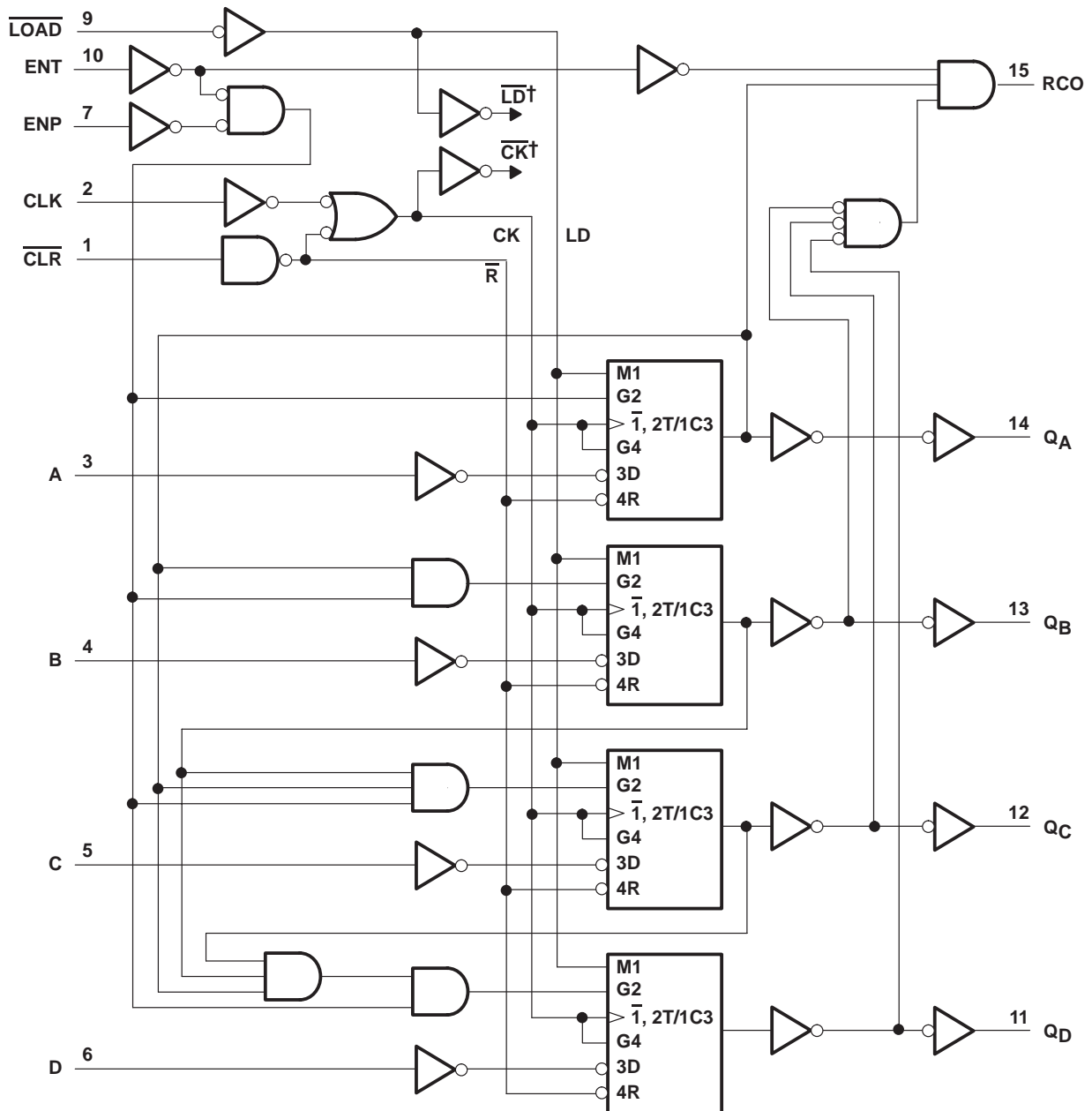
† For simplicity, routing of complementary signals $\overline{LD}$ and $\overline{CK}$ is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.
Pin numbers shown are for the D, DB, DGV, J, NS, PW, and W packages.

logic symbol, each D/T flip-flop
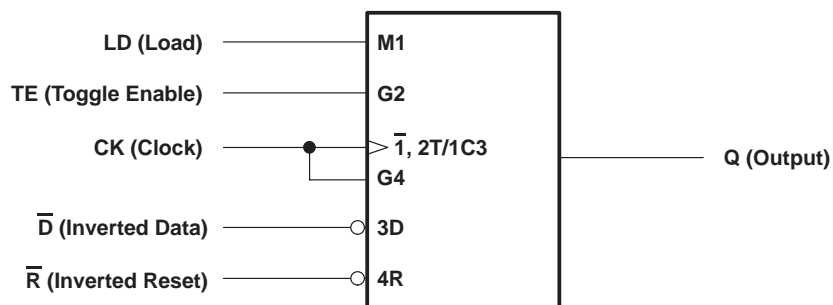
logic diagram, each D/T flip-flop (positive logic)
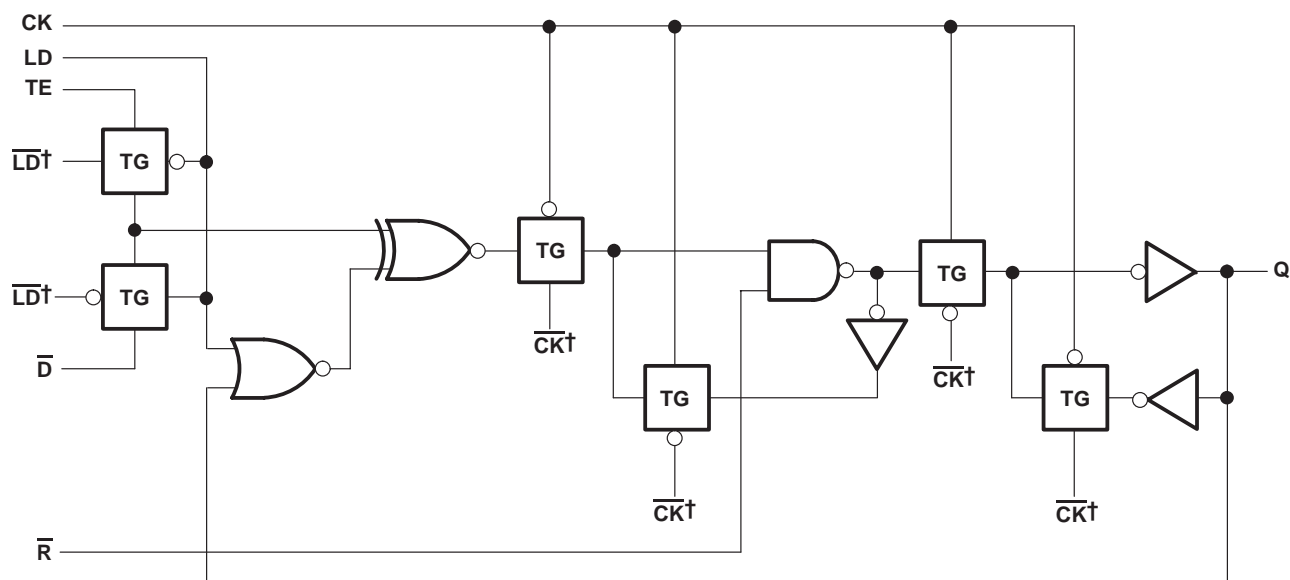
† The origins of $\overline{\text{LD}}$ and $\overline{\text{CK}}$ are shown in the overall logic diagram of the device.

typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

1. Clear outputs to zero (asynchronous)

2. Preset to binary 12

3. Count to 13, 14, 15, 0, 1, and 2

4. Inhibit

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . −0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . −0.5 V to 7 V
Output voltage range applied in high or low state, V_O (see Notes 1 and 2) . . . . −0.5 V to V_{CC} + 0.5 V
Voltage range applied to any output in the power-off state, V_O (see Note 1) . . . . −0.5 V to 7 V
Input clamp current, I_{IK} (V_I < 0) . . . . −20 mA
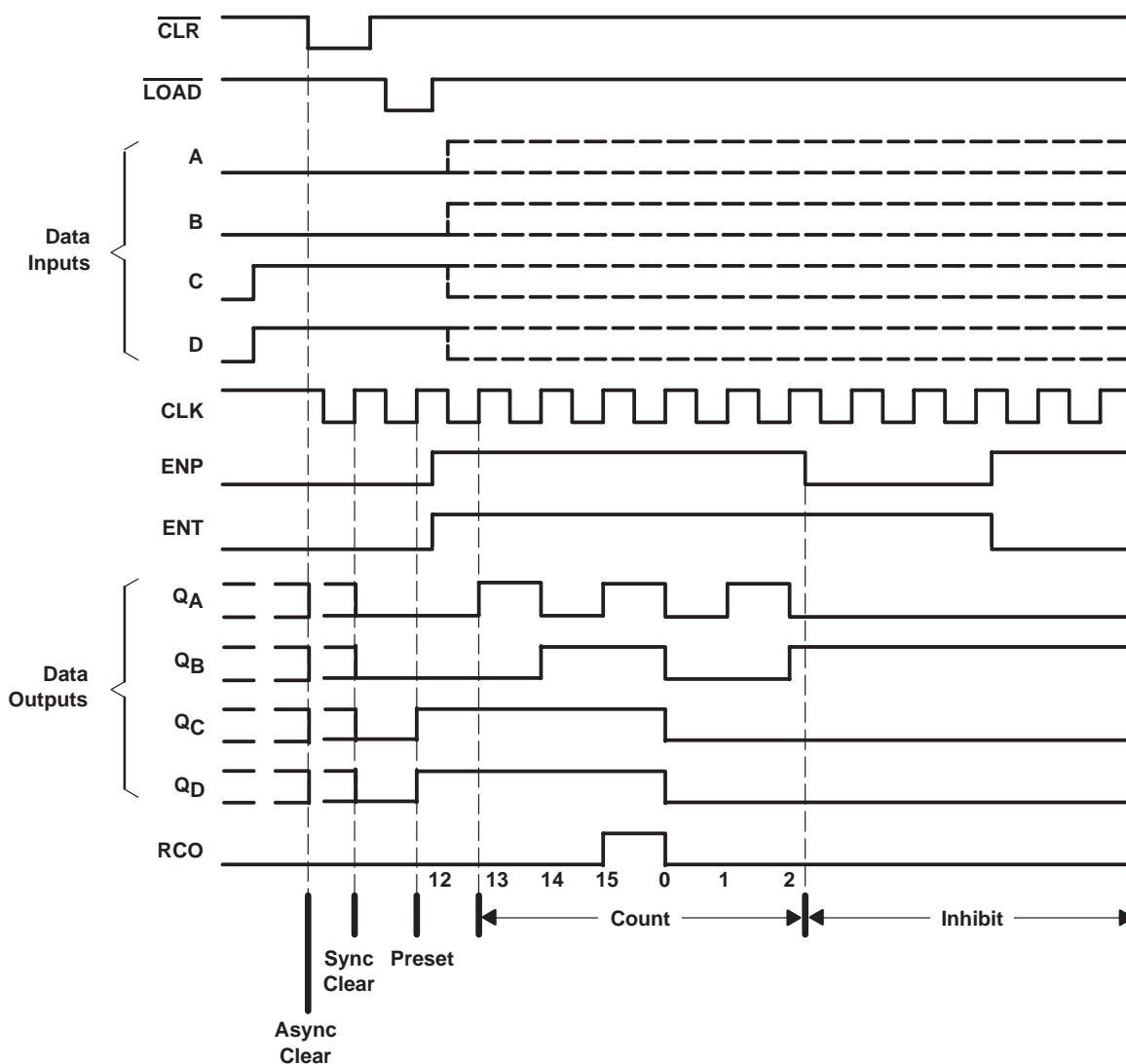Output clamp current, I_{OK} (V_O < 0) . . . . −50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . ±25 mA
Continuous current through V_{CC} or GND . . . . ±50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package . . . . 73°C/W
DB package . . . . 82°C/W
DGV package . . . . 120°C/W
NS package . . . . 64°C/W
PW package . . . . 108°C/W
Storage temperature range, T_{stg} . . . . −65°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and
 functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not
 implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
2. This value is limited to 5.5 V maximum.
3. The package thermal impedance is calculated in accordance with JESD 51-7.

![TEXAS INSTRUMENTS]

recommended operating conditions (see Note 4)

			SN54LV161A		SN74LV161A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	5.5	2	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5		1.5		V
		V_{CC} = 2.3 V to 2.7 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V_{CC} = 3 V to 3.6 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V_{CC} = 4.5 V to 5.5 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.5		0.5	V
		V_{CC} = 2.3 V to 2.7 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
		V_{CC} = 3 V to 3.6 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
		V_{CC} = 4.5 V to 5.5 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 2 V		−50		−50	µA
		V_{CC} = 2.3 V to 2.7 V		−2		−2	mA
		V_{CC} = 3 V to 3.6 V		−6		−6	
		V_{CC} = 4.5 V to 5.5 V		−12		−12	
I_{OL}	Low-level output current	V_{CC} = 2 V		50		50	µA
		V_{CC} = 2.3 V to 2.7 V		2		2	mA
		V_{CC} = 3 V to 3.6 V		6		6	
		V_{CC} = 4.5 V to 5.5 V		12		12	
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 2.3 V to 2.7 V	0	200	0	200	ns/V
		V_{CC} = 3 V to 3.6 V	0	100	0	100	
		V_{CC} = 4.5 V to 5.5 V	0	20	0	20	
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 4:   All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	SN54LV161A			SN74LV161A			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{OH}	I_{OH} = −50 µA	2 V to 5.5 V	V_{CC}−0.1			V_{CC}−0.1			V
	I_{OH} = −2 mA	2.3 V	2			2			
	I_{OH} = −6 mA	3 V	2.48			2.48			
	I_{OH} = −12 mA	4.5 V	3.8			3.8			
V_{OL}	I_{OL} = 50 µA	2 V to 5.5 V			0.1			0.1	V
	I_{OL} = 2 mA	2.3 V			0.4			0.4	
	I_{OL} = 6 mA	3 V			0.44			0.44	
	I_{OL} = 12 mA	4.5 V			0.55			0.55	
I_I	V_I = 5.5 V or GND	0 to 5.5 V			±1			±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			20			20	µA
I_{off}	V_I or V_O = 0 to 5.5 V	0			5			5	µA
C_i	V_I = V_{CC} or GND	3.3 V		1.8			1.8		pF

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timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54LV161A		SN74LV161A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	CLK high or low	7		7		7		ns
		$\overline{CLR}$ low	7		7		7		
t_{su}	Setup time before CLK↑	$\overline{CLR}$	4.5		4.5		4.5		ns
		Data (A, B, C, and D)	7.5		8.5		8.5		
		ENP, ENT	9.5		11		11		
		$\overline{LOAD}$ low	10		11.5		11.5		
t_h	Hold time, all synchronous inputs after CLK↑		1.5		1.5		1.5		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54LV161A		SN74LV161A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	CLK high or low	5		5		5		ns
		$\overline{CLR}$ low	5		5		5		
t_{su}	Setup time before CLK↑	$\overline{CLR}$	2.5		2.5		2.5		ns
		Data (A, B, C, and D)	5.5		6.5		6.5		
		ENP, ENT	7.5		9		9		
		$\overline{LOAD}$ low	8		9.5		9.5		
t_h	Hold time, all synchronous inputs after CLK↑		1		1		1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54LV161A		SN74LV161A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration	CLK high or low	5		5		5		ns
		$\overline{CLR}$ low	5		5		5		
t_{su}	Setup time before CLK↑	$\overline{CLR}$	1.5		1.5		1.5		ns
		Data (A, B, C, and D)	4.5		4.5		4.5		
		ENP, ENT	5		6		6		
		$\overline{LOAD}$ low	5		6		6		
t_h	Hold time, all synchronous inputs after CLK↑		1		1		1		ns

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switching characteristics over recommended operating free-air temperature range,
V_{CC} = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54LV161A		SN74LV161A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	50*	125*		40*		40		MHz
			C_L = 50 pF	30	95		25		25		
t_{pd}	CLK	Q	C_L = 15 pF		7.9*	16.2*	1*	19.5*	1	19.5	ns
		RCO (count mode)			8.9*	17*	1*	20.5*	1	20.5	
		RCO (preset mode)			11.9*	20.6*	1*	24.5*	1	24.5	
	ENT	RCO			8.3*	15.7*	1*	19*	1	19	
t_{PHL}	$\overline{CLR}$	Q			8.8*	17*	1*	20.5*	1	20.5	
		RCO			9.8*	16.6*	1*	20*	1	20	
t_{pd}	CLK	Q	C_L = 50 pF		10.5	19.2	1	22.5	1	22.5	ns
		RCO (count mode)			11.7	20	1	23.5	1	23.5	
		RCO (preset mode)			14.5	23.6	1	27.5	1	27.5	
	ENT	RCO			11	18.7	1	22	1	22	
t_{PHL}	$\overline{CLR}$	Q			11.4	20	1	23.5	1	23.5	
		RCO			12.6	19.6	1	23	1	23	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

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switching characteristics over recommended operating free-air temperature range,
V_{CC} = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C MIN	TYP	MAX	SN54LV161A MIN	MAX	SN74LV161A MIN	MAX	UNIT
f_{max}			C_L = 15 pF*	80*	165*		70*		70		MHz
			C_L = 50 pF	55	125		50		50		
t_{pd}*	CLK	Q	C_L = 15 pF		6	12.8	1*	15*	1	15	ns
		RCO (count mode)			6.7	13.6	1*	16*	1	16	
		RCO (preset mode)			8.6	17.2	1*	20*	1	20	
	ENT	RCO			6.2	12.3	1*	14.5*	1	14.5	
t_{PHL}*	$\overline{CLR}$	Q			6.5	13.6	1*	16*	1	16	
		RCO			7.2	13.2	1*	15.5*	1	15.5	
t_{pd}	CLK	Q	C_L = 50 pF		7.8	16.3	1	18.5	1	18.5	ns
		RCO (count mode)			8.7	17.1	1	19.5	1	19.5	
		RCO (preset mode)			10.6	20.7	1	23.5	1	23.5	
	ENT	RCO			8.3	15.8	1	18	1	18	
t_{PHL}	$\overline{CLR}$	Q			8.4	17.1	1	19.5	1	19.5	
		RCO			9.2	16.7	1	19	1	19	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25°C$ MIN	TYP	MAX	SN54LV161A MIN	MAX	SN74LV161A MIN	MAX	UNIT
f_{max}			C_L = 15 pF	135*	220		115*		115		MHz
			C_L = 50 pF	95	165		85		85		
t_{pd}	CLK	Q	C_L = 15 pF		4.5*	8.1*	1*	9.5*	1	9.5	ns
		RCO (count mode)			5.1*	8.1*	1*	9.5*	1	9.5	
		RCO (preset mode)			6.3*	10.3*	1*	12*	1	12	
	ENT	RCO			4.8*	8.1*	1*	9.5*	1	9.5	
t_{PHL}	$\overline{CLR}$	Q			4.9*	9	1*	10.5*	1	10.5	
		RCO			5.5*	8.6*	1*	10*	1	10	
t_{pd}	CLK	Q	C_L = 50 pF		5.9	10.1	1	11.5	1	11.5	ns
		RCO (count mode)			6.6	10.1	1	11.5	1	11.5	
		RCO (preset mode)			7.8	12.3	1	14	1	14	
	ENT	RCO			6.1	10.1	1	11.5	1	11.5	
t_{PHL}	$\overline{CLR}$	Q			6.3	11	1	12.5	1	12.5	
		RCO			6.9	10.6	1	12	1	12	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

PARAMETER		SN74LV161A MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.3	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		−0.2	−0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		3		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 10 MHz	3.3 V	23.6	pF
			5 V	25.8	

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PARAMETER MEASUREMENT INFORMATION

LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

LOAD CIRCUIT FOR 3-STATE AND OPEN-DRAIN OUTPUTS

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}

VOLTAGE WAVEFORMS PULSE DURATION

VOLTAGE WAVEFORMS SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS

VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
   B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control.
       Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
   C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
   D. The outputs are measured one at a time, with one input transition per measurement.
   E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
   F. t_{PZL} and t_{PZH} are the same as t_{en}.
   G. t_{PHL} and t_{PLH} are the same as t_{pd}.
   H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGE OPTION ADDENDUM

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN74LV161AD	Obsolete	Production	SOIC (D) | 16	-	-	Call TI	Call TI	-40 to 85	LV161A
SN74LV161ADBR	Active	Production	SSOP (DB) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161ADBR.A	Active	Production	SSOP (DB) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161ADGVR	Active	Production	TVSOP (DGV) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161ADGVR.A	Active	Production	TVSOP (DGV) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161ADR	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161ADR.A	Active	Production	SOIC (D) | 16	2500 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161ANSR	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV161A
SN74LV161ANSR.A	Active	Production	SOP (NS) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	74LV161A
SN74LV161APW	Obsolete	Production	TSSOP (PW) | 16	-	-	Call TI	Call TI	-40 to 85	LV161A
SN74LV161APWR	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161APWR.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161APWRG4	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	No	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161APWRG4	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161APWRG4.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161APWRG4.A	Active	Production	TSSOP (PW) | 16	2000 | LARGE T&R	No	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LV161A
SN74LV161APWT	Obsolete	Production	TSSOP (PW) | 16	-	-	Call TI	Call TI	-40 to 85	LV161A

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

User Direction of Feed

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV161ADBR	SSOP	DB	16	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
SN74LV161ADGVR	TVSOP	DGV	16	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV161ADR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LV161ANSR	SOP	NS	16	2000	330.0	16.4	8.1	10.4	2.5	12.0	16.0	Q1
SN74LV161APWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LV161APWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

PACKAGE MATERIALS INFORMATION

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV161ADBR	SSOP	DB	16	2000	353.0	353.0	32.0
SN74LV161ADGVR	TVSOP	DGV	16	2000	353.0	353.0	32.0
SN74LV161ADR	SOIC	D	16	2500	353.0	353.0	32.0
SN74LV161ANSR	SOP	NS	16	2000	353.0	353.0	32.0
SN74LV161APWR	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74LV161APWRG4	TSSOP	PW	16	2000	353.0	353.0	32.0

C

SEATING PLANE

0.1 C

8.2 / 7.4 TYP

A

PIN 1 ID AREA

14X 1.27

1

16

2X 8.89

10.4 / 10.0 NOTE 3

8

9

16X 0.51 / 0.35

⊕ 0.25Ⓜ C A B

B

5.4 / 5.2 NOTE 4

2.00 MAX

SEE DETAIL A

0.15 TYP

0.25

GAGE PLANE

0.3 / 0.1

0° - 10°

1.05 / 0.55

(1.25)

DETAIL A
TYPICAL

4220735/A   12/2021

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.

16X (1.85)

SYMM

SEE
DETAILS

1

16X (0.6)

16

SYMM

14X (1.27)

8

9

(R0.05) TYP

(7)

LAND PATTERN EXAMPLE
SCALE:7X

METAL

SOLDER MASK
OPENING

SOLDER MASK
OPENING

METAL

0.07 MAX
ALL AROUND

0.07 MIN
ALL AROUND

NON SOLDER MASK
DEFINED

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220735/A   12/2021

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

16X (1.85)

SYMM

1

16

16X (0.6)

SYMM

14X (1.27)

8

9

(R0.05) TYP

(7)

SOLDER PASTE EXAMPLE
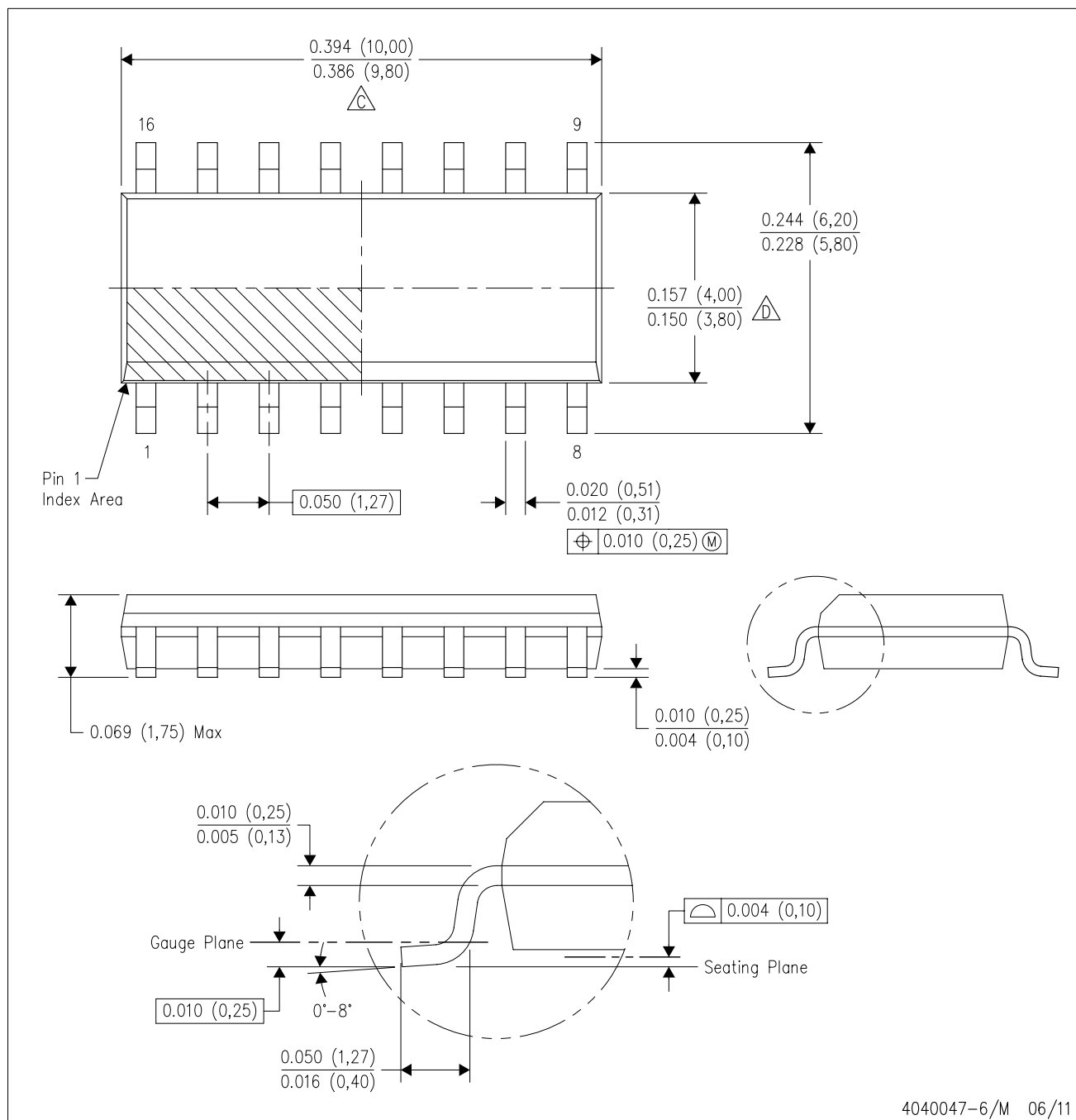BASED ON 0.125 mm THICK STENCIL
SCALE:7X
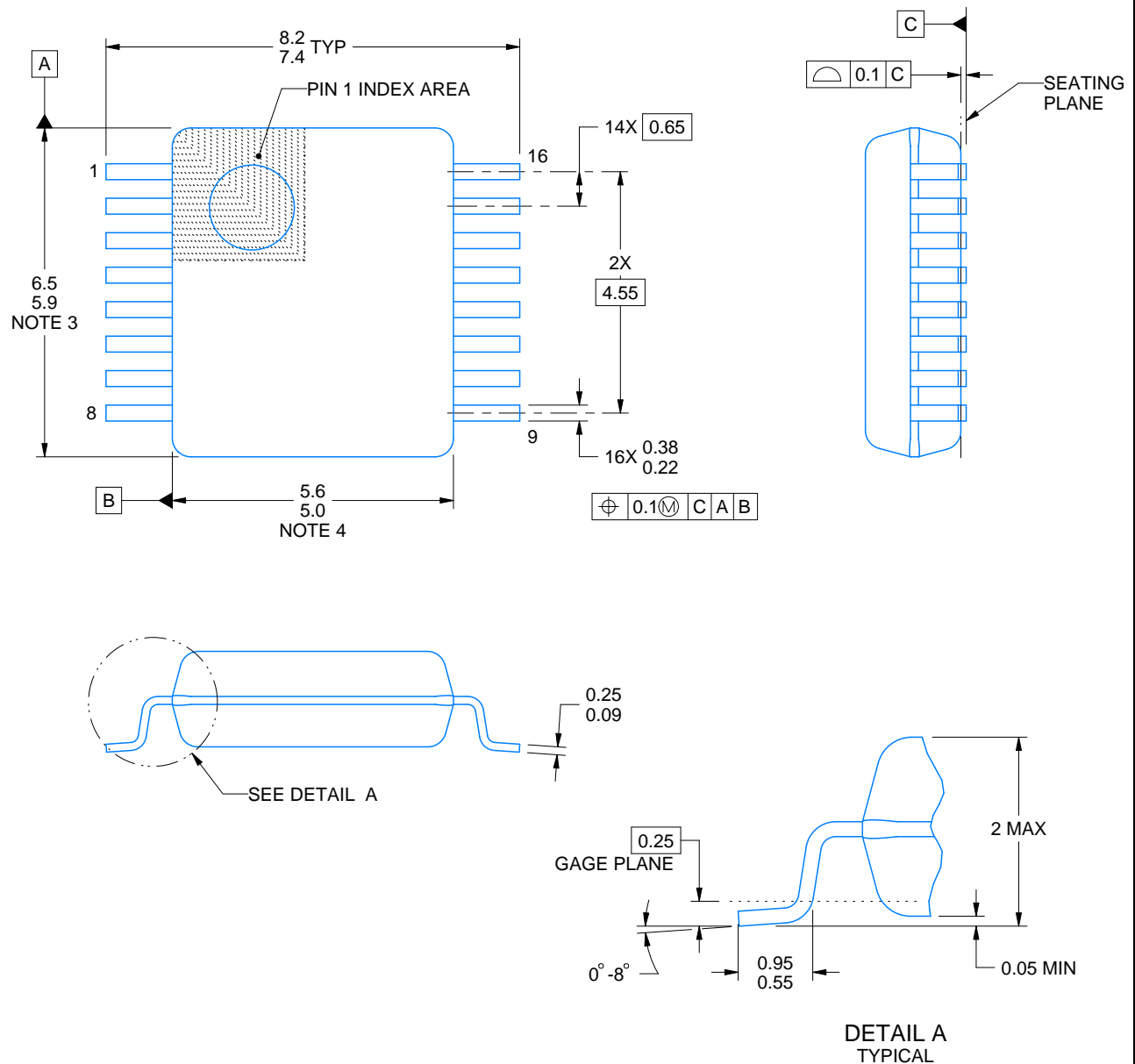
4220735/A   12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate
   design recommendations.
8. Board assembly site may have different recommendations for stencil design.

D (R−PDSO−G16)   PLASTIC SMALL OUTLINE

0.394 (10,00)
0.386 (9,80)
C

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80)
D

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.005 (0,13)

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°

0.050 (1,27)
0.016 (0,40)

4040047-6/M   06/11

NOTES: A. All linear dimensions are in inches (millimeters).
        B. This drawing is subject to change without notice.
        C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
        D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
        E. Reference JEDEC MS−012 variation AC.

TEXAS INSTRUMENTS
www.ti.com

8.2
7.4 TYP

A

PIN 1 INDEX AREA

1

16

14X 0.65

6.5
5.9
NOTE 3

2X
4.55

8

9

B

5.6
5.0
NOTE 4

16X 0.38
0.22

⊕ 0.1 Ⓜ C A B

C

⌒ 0.1 C

SEATING
PLANE

0.25
0.09

SEE DETAIL A

0.25

GAGE PLANE

2 MAX

0° -8°

0.95
0.55

0.05 MIN

DETAIL A
TYPICAL

4220763/A   05/2022

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. Reference JEDEC registration MO-150.

16X (1.85)

1

16X (0.45)

14X (0.65)

8

SYMM

(R0.05) TYP

16

SYMM

9

(7)

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK OPENING

METAL

EXPOSED METAL

0.05 MAX
ALL AROUND

NON-SOLDER MASK
DEFINED
(PREFERRED)

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

EXPOSED METAL

0.05 MIN
ALL AROUND

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220763/A   05/2022

NOTES: (continued)

5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

16X (1.85)

SYMM

1

16X (0.45)

(R0.05) TYP

16

SYMM

14X (0.65)

8

9

(7)

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220763/A   05/2022

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

NS (R-PDSO-G)**   PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

	PINS **	14	16	20	24
DIM					
A	MAX	10,50	10,50	12,90	15,30
A	MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
          B.   This drawing is subject to change without notice.
          C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DGV (R-PDSO-G**) **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN

PINS ** DIM	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

6.6
6.2 TYP

A

PIN 1 INDEX AREA

14X 0.65

16

1

5.1
4.9
NOTE 3

2X
4.55

8

B

4.5
4.3
NOTE 4

9

16X 0.30
0.17

⊕ 0.1 Ⓜ C A B

SEATING PLANE

C

◯ 0.1 C

4X (0° -12°)

1.2 MAX

SEE DETAIL A

(0.15) TYP

0.25
GAGE PLANE

0.15
0.05

0° -8°

0.75
0.50

DETAIL A
TYPICAL

4220204/B   12/2023

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

16X (1.5)

SYMM

1

16X (0.45)

(R0.05) TYP

16

SYMM

14X (0.65)

8

9

(5.8)

LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

SOLDER MASK
OPENING

METAL

EXPOSED METAL

0.05 MAX
ALL AROUND

NON-SOLDER MASK
DEFINED
(PREFERRED)

METAL UNDER
SOLDER MASK

SOLDER MASK
OPENING

EXPOSED METAL

0.05 MIN
ALL AROUND

SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4220204/B   12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

16X (1.5)

SYMM

1

16X (0.45)

(R0.05) TYP

16

SYMM

14X (0.65)

8

9

(5.8)

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B   12/2023

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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